Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	20996	257/678,684,685,686,687,690, 698,700,734,737,738,777,780, 787,790,792,793,794.ccls. 438/106,121,613.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 13:57
S2	1073	die and (mount or mounting) and (bonding pad) and interposer and (bump or ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 13:57
S3	20996	257/678,684,685,686,687,690, 698,700,734,737,738,777,780, 787,790,792,793,794.ccls. 438/106,121,613.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 13:57
S4	387	S2 and S3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/13 13:58
S5	163	S2 and S3 and (encapsulant or encapsulate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 14:20
S6	1198	die and (mount or mounting) and (bonding pad) and interposer and (bump or ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 14:21
S7	22218	257/678,684,685,686,687,690, 698,700,734,737,738,777,780, 787,790,792,793,794.ccls. 438/106,121,613.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 14:21
S8	14	S6 and S7 and (encapsulant or encapsulate) and @pd>"20050513"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 14:24
S9	1	((die adj mounting adj substrate) and (conductive adj contact) and (semiconductor adj die) and (pad-mounting adj surface) and (bonding adj pad) and (dielectric adj interposer) and (conductive adj strip) and encapsulant).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/26 14:25